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(54) **SUBSTRATE SUPPORTS AND TRANSFER APPARATUS FOR SUBSTRATE DEFORMATION**

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(57)

ABSTRACT

Embodiments of the present disclosure relate to substrate supports, transfer apparatus, processing chambers, and related components and methods, for substrate deformation (e.g., bowing). In one or more implementations, a substrate used in relation to the present disclosure can be deformed (e.g., bowed) before and/or during processing (such as epitaxial deposition). In one implementation, a substrate support applicable for use in semiconductor manufacturing operations includes a support body. The support body includes an outer surface, a recessed surface that is recessed relative to the outer surface, and a pocket surface between the outer surface and the recessed surface. The recessed surface and the pocket surface at least partially define a pocket of the support body. The support body includes a plurality of supports protruding relative to the recessed surface. The substrate support includes a barrier interfacing with the plurality of supports. The barrier includes a plurality of barrier supports.

